Driver Transistors

NPN Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage MMBTA05LT1 MMBTA06LT1, SMMBTA06LT1	V _{CEO}	60 80	Vdc
Collector – Base Voltage MMBTA05LT1 MMBTA06LT1, SMMBTA06LT1	V _{CBO}	60 80	Vdc
Emitter – Base Voltage	V_{EBO}	4.0	Vdc
Collector Current – Continuous	Ι _C	500	mAdc
Electrostatic Discharge	ESD	HBM Class 3B MM Class C CDM Class IV	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C	PD	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C	P _D	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA}	417	°C/W
Junction and Storage Temperature	T _J , T _{stq}	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

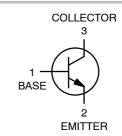
1. FR–5 = 1.0 \times 0.75 \times 0.062 in.

2. Alumina = 0.4 \times 0.3 \times 0.024 in. 99.5% alumina.



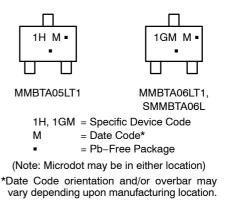
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MARKING DIAGRAMS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

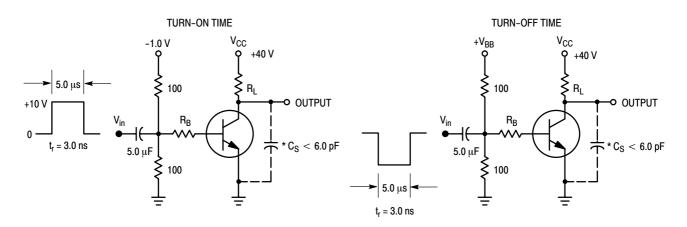
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Char	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (N $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	Note 3) MMBTA05 MMBTA06, SMMBTA06	V _{(BR)CEO}	60 80		Vdc
Emitter – Base Breakdown Voltage ($I_E = 100 \ \mu Adc, I_C = 0$)		V _{(BR)EBO}	4.0	-	Vdc
Collector Cutoff Current ($V_{CE} = 60 \text{ Vdc}, I_B = 0$)		I _{CES}	-	0.1	μAdc
Collector Cutoff Current ($V_{CB} = 60 \text{ Vdc}, I_E = 0$) ($V_{CB} = 80 \text{ Vdc}, I_E = 0$)	MMBTA05 MMBTA06, SMMBTA06	I _{CBO}	-	0.1 0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain ($I_C = 10 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}$) ($I_C = 100 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}$)		h _{FE}	100 100		-
Collector – Emitter Saturation Voltage ($I_C = 100$ mAdc, $I_B = 10$ mAdc)		V _{CE(sat)}	-	0.25	Vdc
Base – Emitter On Voltage (I _C = 100 mAdc, V _{CE} = 1.0 Vdc)		V _{BE(on)}	-	1.2	Vdc

Current – Gain – Bandwidth Product (Note 4)	f _T	100	-	MHz
(I _C = 10 mA, V _{CE} = 2.0 V, f = 100 MHz)				

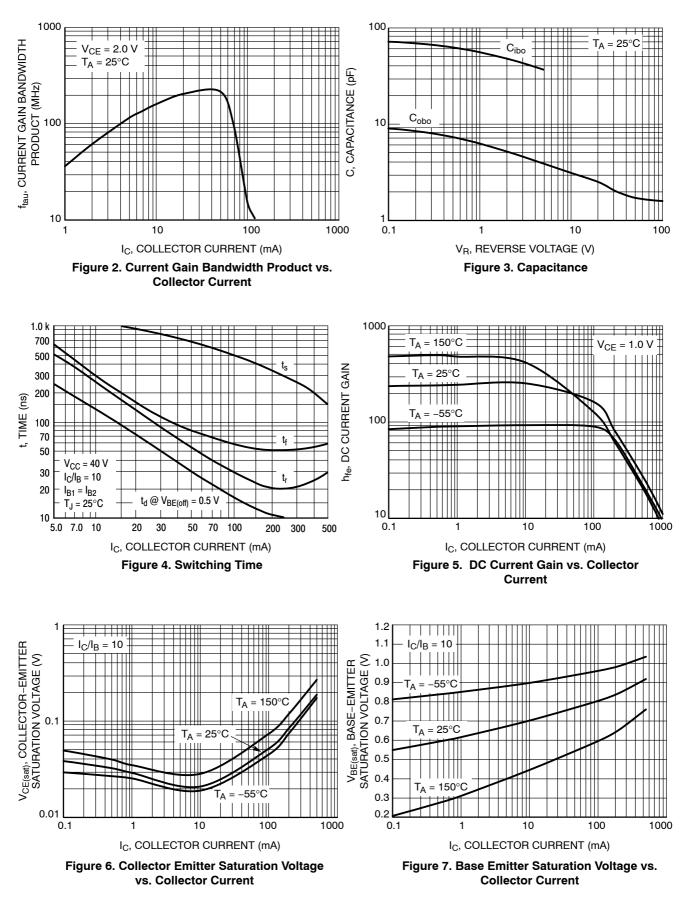
3. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

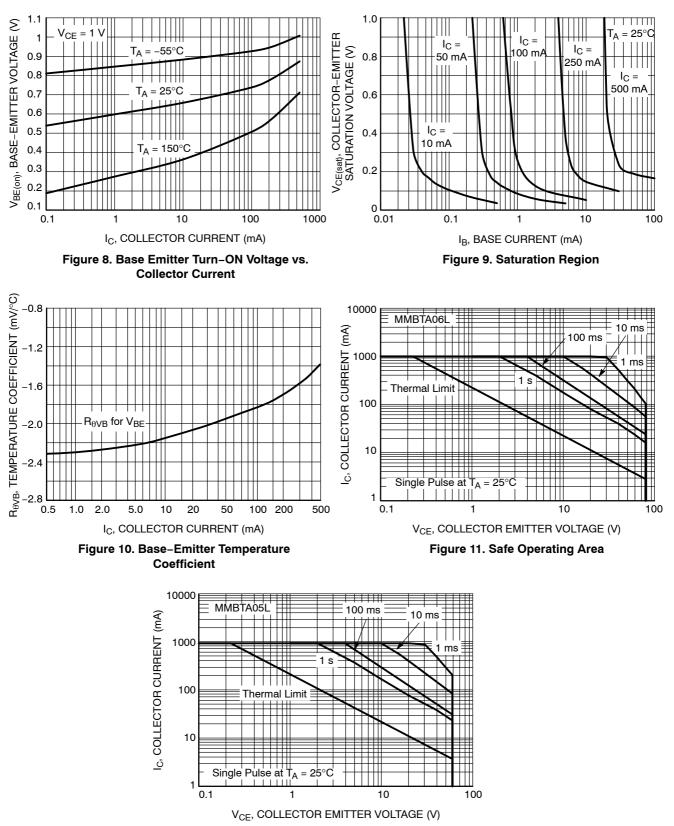
4. f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.



*Total Shunt Capacitance of Test Jig and Connectors For PNP Test Circuits, Reverse All Voltage Polarities

Figure 1. Switching Time Test Circuits







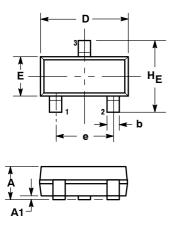
ORDERING INFORMATION

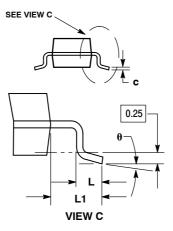
Device	Package	Shipping [†]
MMBTA05LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBTA05LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
MMBTA06LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
SMMBTA06LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBTA06LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
SMMBTA06LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AP





Thombolond, on date bonno.						
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

1 DIMENSIONING AND TOLEBANCING PER ANSI Y14 5M 1982

MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM

THICKNESS OF BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,

CONTROLLING DIMENSION: INCH.

PROTEILSIONS OR GATE BURDS

STYLE 6: PIN 1. BASE 2. EMITTER

NOTES:

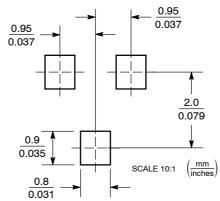
2

3

4.

3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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